ABSTRACT

An encapsulation resin composition for preapplication, comprising (a) an epoxy resin, and (b) a curing agent having flux activity, wherein the tack after B-staging is at least 0 gf/5 mmϕ and at most 5 gf/5 mmϕ, and the melt viscosity at 130 °C is at least 0.01 Pa·s and at most 1.0 Pa·s; a preapplied encapsulated component and semiconductor device using the composition, and a process of fabrication thereof. The resin composition is less susceptible to air entrapment during provisional placement of semiconductor chips, and excels in workability and reliability.